



## Deliver on Consistency, Reliability and Quality

### MESSAGE



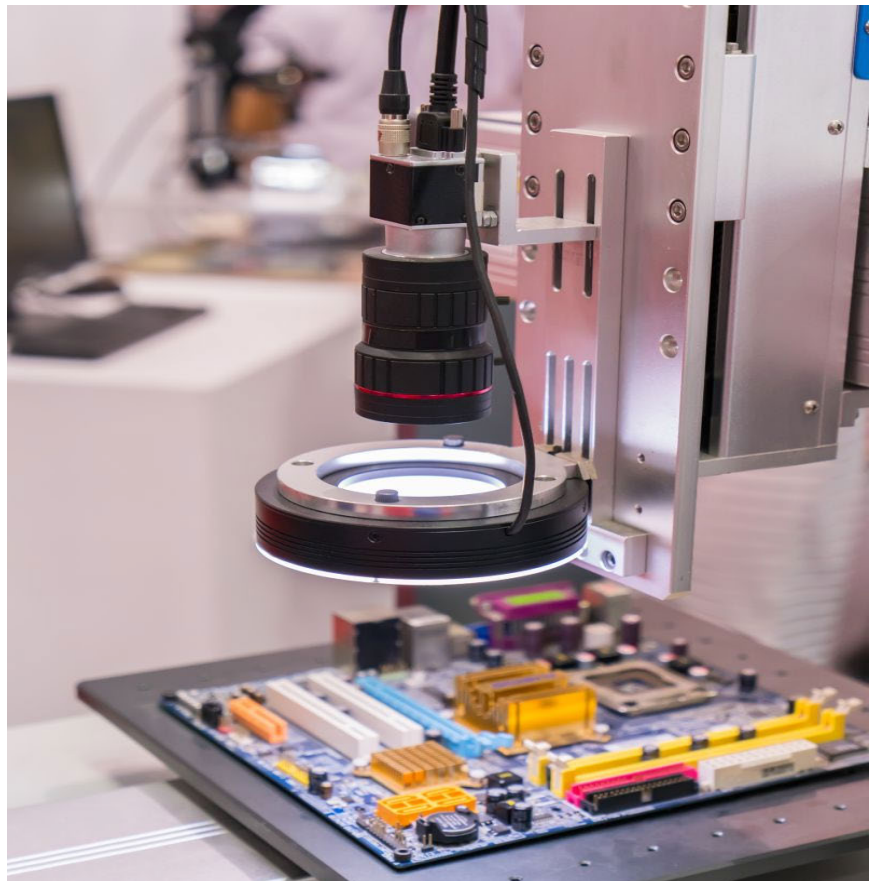
**David Bergman**  
Vice President  
(Standards & Technology) IPC

IPC enables reliable, high-quality electronics by developing the trusted standards that drive the global electronics industry's success. Implemented industry-wide, our standards simply communicate and clarify expectations for everyone within the industry. IPC standards help ensure superior quality, reliability and consistency in electronics manufacturing.

IPC has over 300+ active multilingual industry standards, covering nearly every stage of the electronics product development cycle. There are more than 3,000 electronic industry professionals participating in the development of these standards.

### Call for Volunteer

IPC is seeking volunteers to participate in the development of a new standard for automated optical inspection (AOI) systems to define, set up, establish, and apply process control for manufacturing printed board assemblies, including general and specific process and equipment conditions. At a minimum, this standard will cover requirements for operating and inspection parameters, vision systems, lighting conditions, calibration, detectability, resolution, threshold limits and process windows, program setups, measurement system analysis (MSA), and maintenance and verification protocols. If you have an interest in participating in the new IPC task group that will be forming for this activity, email [answers@ipc.org](mailto:answers@ipc.org) and reference the AOI process control standard group. Once a group is formed, someone from IPC staff will contact you. [#BuildElectronicsBetter](https://twitter.com/BuildElectronicsBetter)



## IPC India - Standards Development Activity

February 2023, IPC India had a series of Standard Development Activities in presence of Mr. David Bergman (VP-Standard) and Mr. Gaurab Majumdar (ED-IPC India). During this drive, engagement with 49 India member companies for EMS, Wire Harness and PCB Design came on one platform and discussed on the next actions for Standard Development activities from India region.



**Gaurab Majumdar (ED-IPC India), Saurabh K Saxena (HOD Standards, India), David Bergman (VP-Standards)**

During these meetings, a significant development has been done by creating 'EMS' and 'Cable and Wire Harness' India Regional Teams. The more members will be added soon in the team, who couldn't join this meeting.

### IPC EMS/WH Committee for India region



**EMS**

**Cable and Wire Harness**



IPC has received proposals for three new projects for additively manufactured electronics (AME):

- A standard to establish and define the qualification and performance requirements for additively manufactured electronics
- A visual inspection standard to describe the target, acceptable, and nonconforming conditions that are either externally or internally observable on additively manufactured electronics
- New test coupons to support the qualification and performance requirements standard

If you have an interest in participating in one or more of these new activities, email [answers@ipc.org](mailto:answers@ipc.org) and note the activities that interest you. Once new task groups for these activities have been approved, the staff liaison will reach out to you. [#BuildElectronicsBetter](https://twitter.com/BuildElectronicsBetter)

## Update : India\_Sri Lanka Regional Committee

IPC India has developed following India\_Sri Lanka Regional Teams for discussing and recommending the inputs from India and Sri Lanka industry experts for the upcoming new revisions:

- EMS Committee : IPC-A-610, J-STD-001 and IPC-7711/7721 Standards
- Cable and Wire Harness Committee : IPC-A-620 Standard

Having these committee at India region, the proposed changed for new revision of IPC-A-610, J-STD-001, IPC 7711/21 and IPC/WHMA-A-620 standards may be discussed and recommend the inputs from India and Sri Lanka industry experts for the upcoming new revisions.

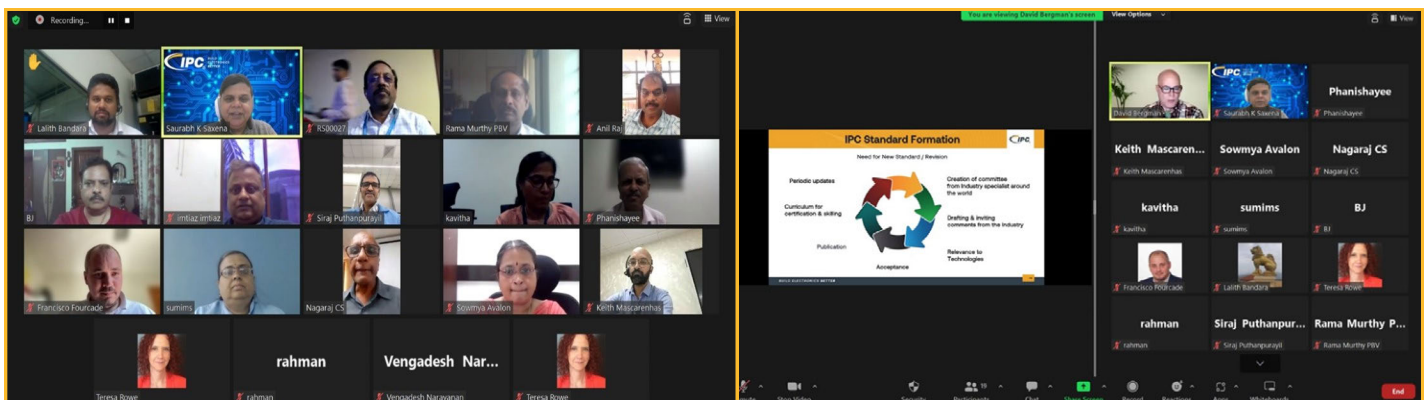
With this initiative, IPC India region has also now actively participating in line with Europe and China region in suggesting comments for the global IPC standards.

Thanks to the regional member companies for coming at a common platform and joining for providing the inputs for global standards.

### IPC-A-610 and J-STD-001 Standards Regional Team Meeting

21st April 2023, IPC India virtually organized first time ever the meeting of 'Regional Team of India and Sri Lanka Standard development Team' consisting 22 members from 20 EMS organizations joined together at a single platform.

During this meeting, the proposed changed for new revision of IPC-A-610 and J-STD-001 standards in FDIR (Final Draft for Industry Review) had been discussed and recommended the inputs for upcoming new revisions.



**IPC-A-610 and J-STD-001 Standards Regional Team Meeting**

### IPC-A-620 Standards Regional Team Meeting

25th April 2023, IPC India also organized IPC-A-620 (Requirements and Acceptance for Cable and Wire Harness Assemblies) Standards Regional Team meeting consisting 20 industry experts from 16 prominent organizations in India and Sri Lanka.



## Standards : Current Status

### Final Draft for Industry Review

|                          |  |
|--------------------------|--|
| <b>IPC-1782B</b>         | Standard for Manufacturing and Supply Chain Traceability of Electronic Products        |
| <b>IPC-4105</b>          | Specification for Metal Base Copper Clad laminates for Rigid Printed Boards            |
| <b>IPC-6012F</b>         | Qualification and Performance Specification for Rigid Printed Boards                   |
| <b>IPC-9797A</b>         | Press-fit Standard for Automotive Requirements and other High-Reliability Applications |
| <b>IPC-A-610J</b>        | Acceptability of Electronic Assemblies   |
| <b>IPC/WHMA-A-620E-S</b> | Space and Military Applications Electronic Hardware Addendum to IPC/WHMA-A-620E.       |
| <b>J-STD-001J</b>        | Requirements for Soldered Electrical and Electronic Assemblies                         |

### Working Draft

|                              |  |
|------------------------------|--|
| <b>IPC-1753A</b>             | Laboratory Report Standard   |
| <b>IPC-1783</b>              | International Standard for Component-Level Authentication (CLA)  |
| <b>IPC-2221C</b>             | Generic Standard on Printed Board Design   |
| <b>IPC-2591, Version 1.7</b> | Connected Factory Exchange (CFX)   |
| <b>IPC-7077</b>              | Requirements and Acceptance of Wire Bonding in the Microelectronic Assembly  |
| <b>IPC-7095E</b>             | Design and Assembly Process Implementation for Ball Grid Arrays (BGAs)   |
| <b>IPC-7251</b>              | Generic Requirements for Through-Hole Design and Land Pattern Standard   |
| <b>IPC-7530B</b>             | Guidelines for Temperature Profiling for Mass Soldering Processes (Reflow & Wave)  |
| <b>IPC-7621A</b>             | Guideline for Design, Material Selection and General Application of Encapsulation of Electronic Circuit Assembly by Low Pressure Molding with Thermoplastics |
| <b>IPC-8921A</b>             | Requirements for Woven, Knitted and Braided Electronic Textiles (E-Textiles) Integrated with Conductive Yarns and/or Wires                                   |
| <b>IPC-8981</b>              | Quality and Reliability of E-Textiles Wearables  |
| <b>IPC-9242</b>              | Guidelines for Microsection Evaluation   |
| <b>IPC-A-600M</b>            | Acceptability of Printed Boards  |
| <b>IPC-HDBK-005A</b>         | Guide to Solder Paste Assessment   |
| <b>IPC-SM-840F</b>           | Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials  |
| <b>IPC/JPCA-8911</b>         | Requirements for Conductive Yarns for E-Textiles Applications  |



For more information, please contact Mr. Saurabh K Saxena (IPC Liaison @ IPC India) for any clarifications on India Standard Development activities.